

MEMS Passive Latching Mechanical Shock Sensor

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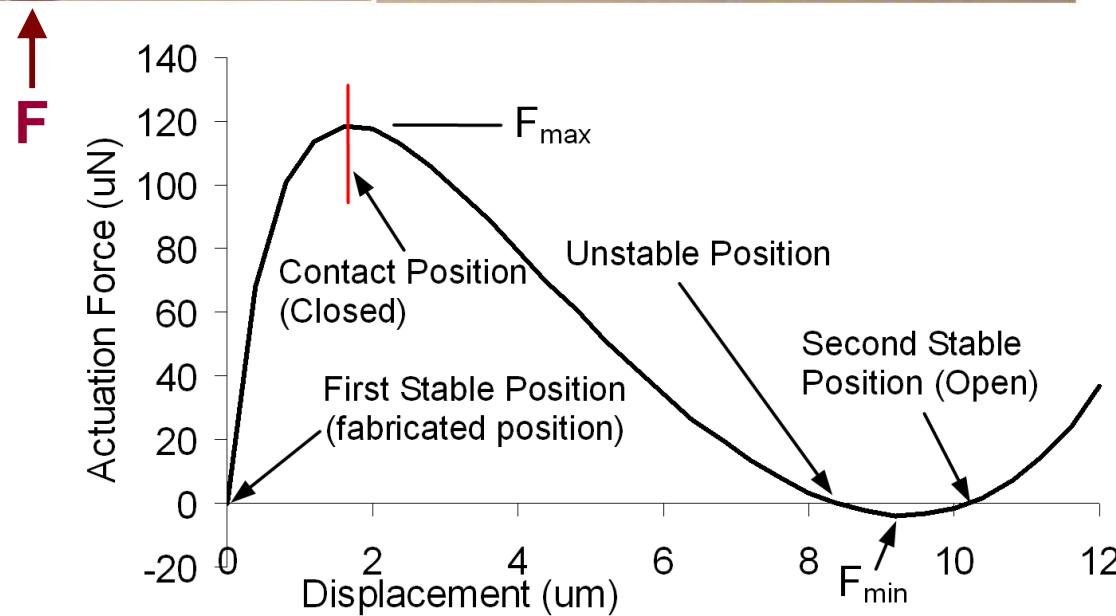
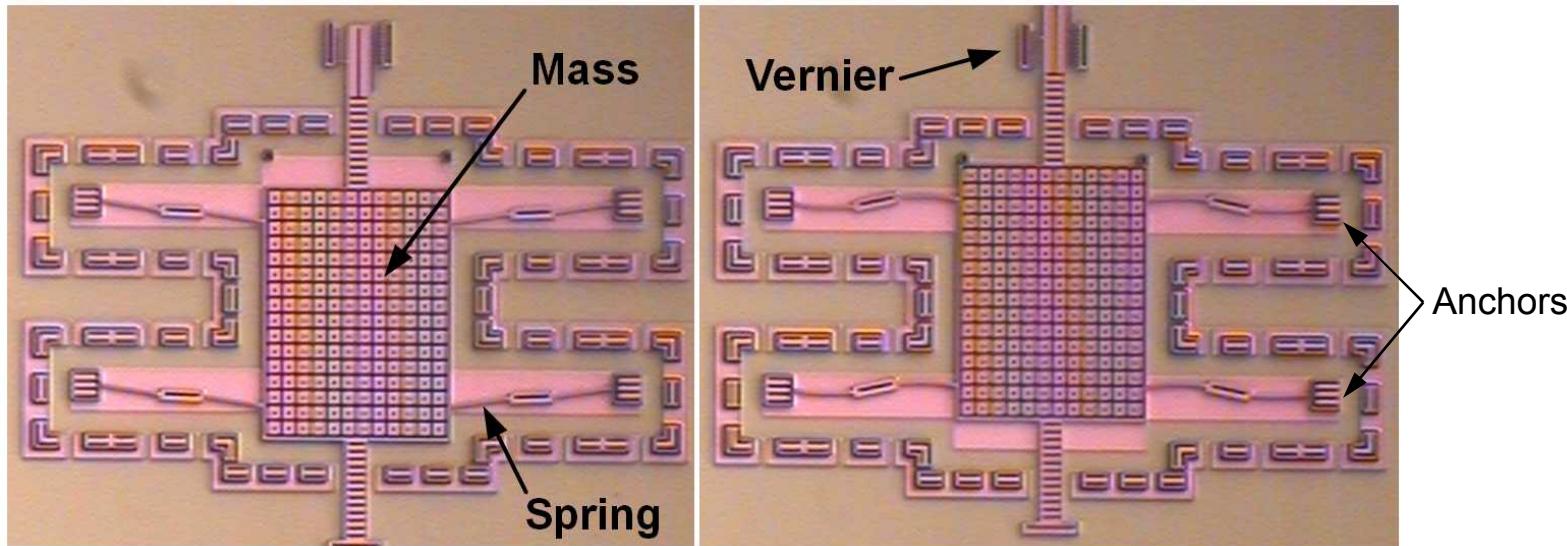


Motivation

- **Low Power**
 - Sense an inertial event (shock, impact, vibration) without requiring power before, during, or after the event
- **Latching**
 - After sensing an event, the device remains in a stable state until interrogated
- **Sense and Survive High-g Impacts (100g's – 25000g's)**
 - Shipping, Handling, Normal Operation (< 100g)
 - Rough handling, undamped impacts (100 – 1000g)
 - Pyrotechnic shock or "Pyroshock" (300g – 300kg)
- **Self-Test**
 - Opening and closing the switch prior to an inertial event
- **Reusable**
 - Ability to unlatch and reset
- **Small Size**
 - Multiple devices on a single chip for redundancy, arrays of thresholds, and/or multiple sense directions
- **Electrical Readout**
 - Allows automation and eases system integration
 - Continuity check (Metal-to-metal contacts provide detectable switch closure)
- **Frictionless motion**
 - Important in a MEMS device for reliable performance
 - Latch behavior based on force differential rather than mechanical latches

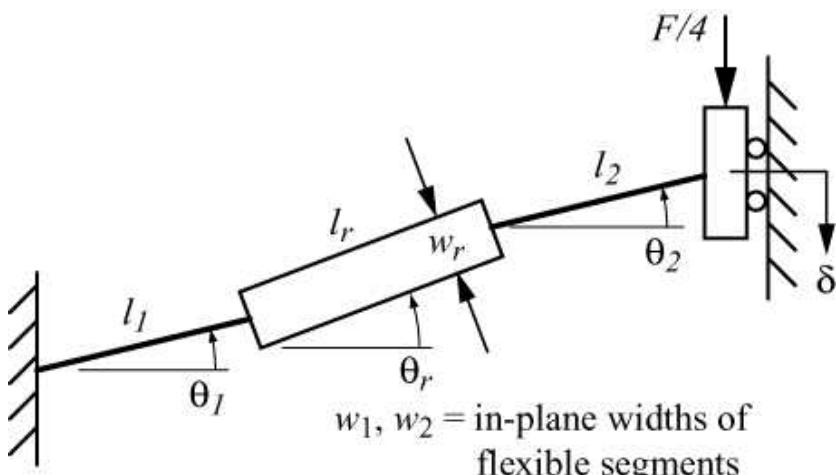
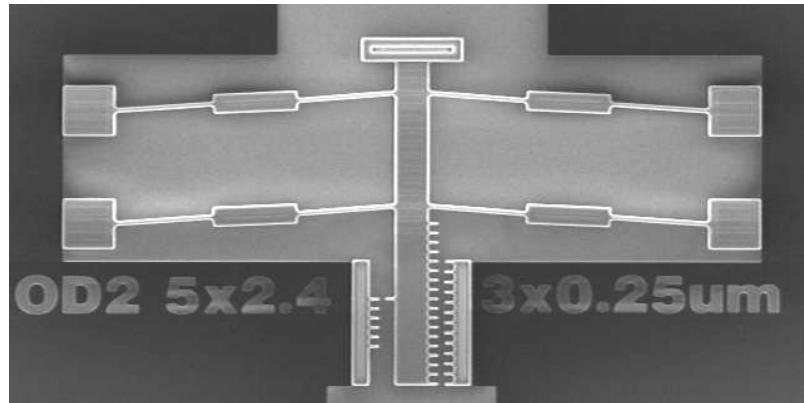


Bistable Micro Mechanism with Inertial Mass





Design and Modeling

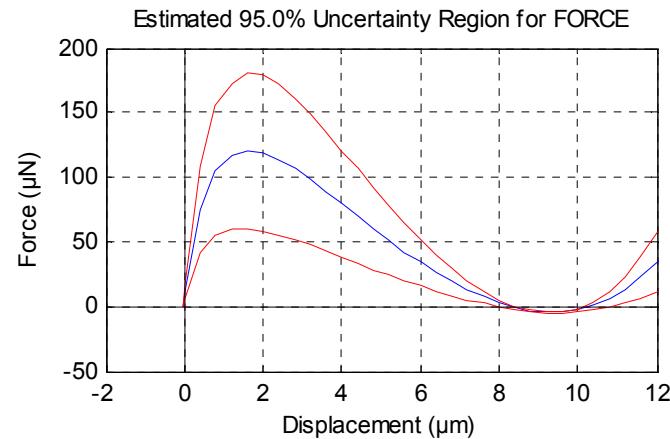


Main Design Parameters

- Beam lengths: L_1, L_2, L_r
- Beam angles: $\theta_1, \theta_2, \theta_r$
- Beam widths: w_1, w_2

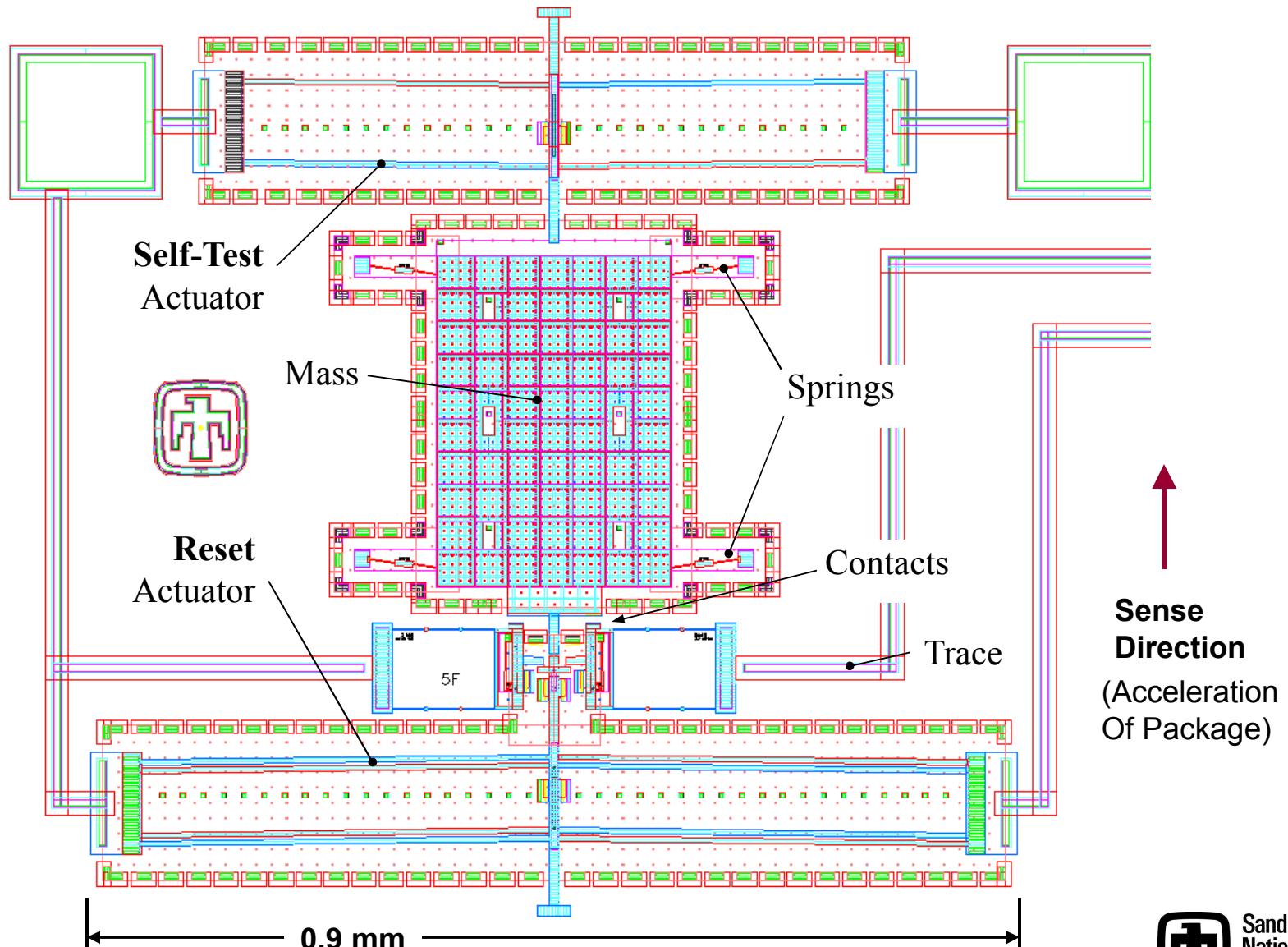
Robust Optimization

Minimize sensitivity to process variations.



IMAGES FROM: Wittwer, J.W., Baker, M.S., and Howell, L.L., "Robust Design and Model Validation of Nonlinear Compliant Micromechanisms," *Journal of Microelectromechanical Systems*, Vol. 15, No. 1, pp. 33-41, 2006.

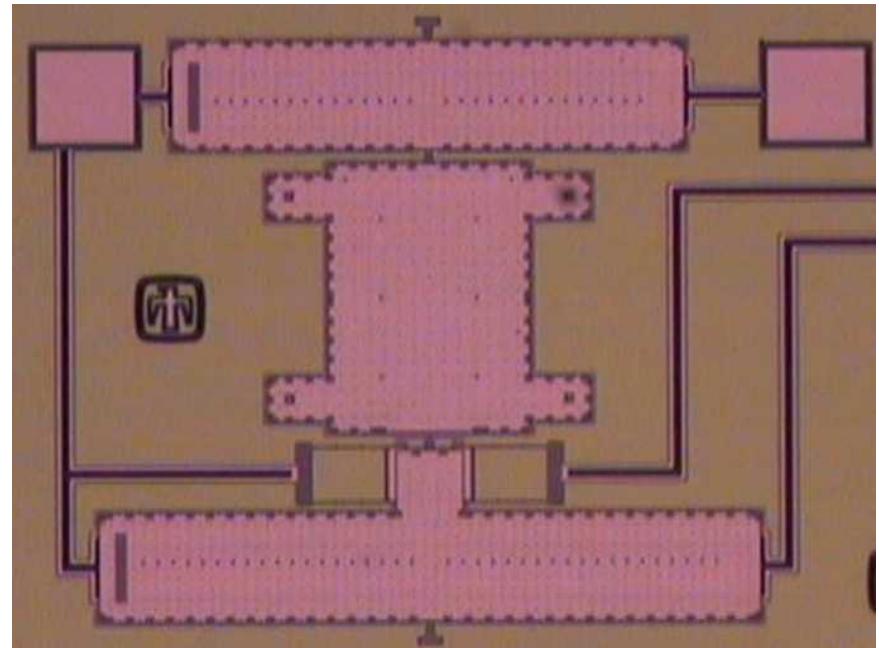
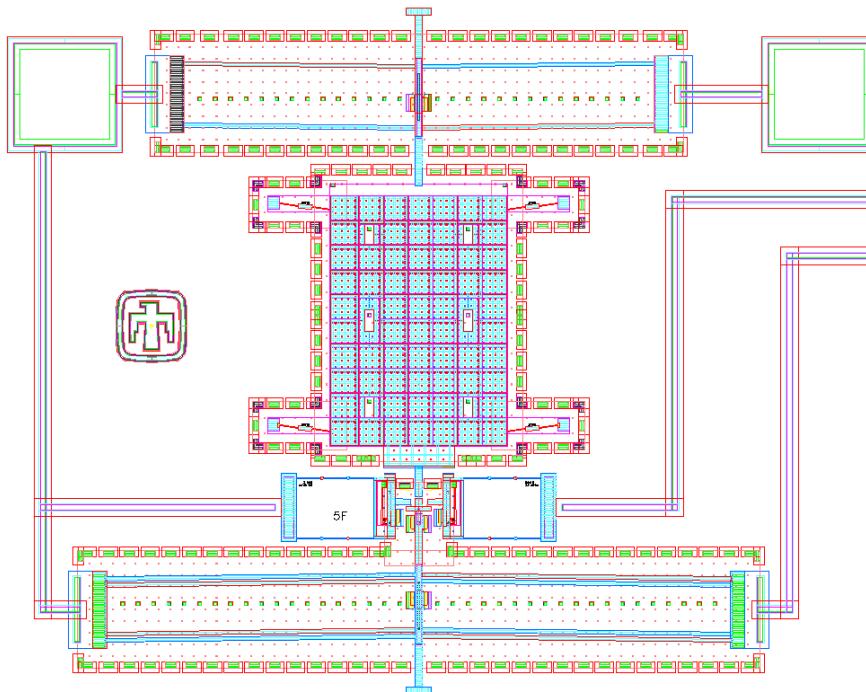
Fabrication and Operation



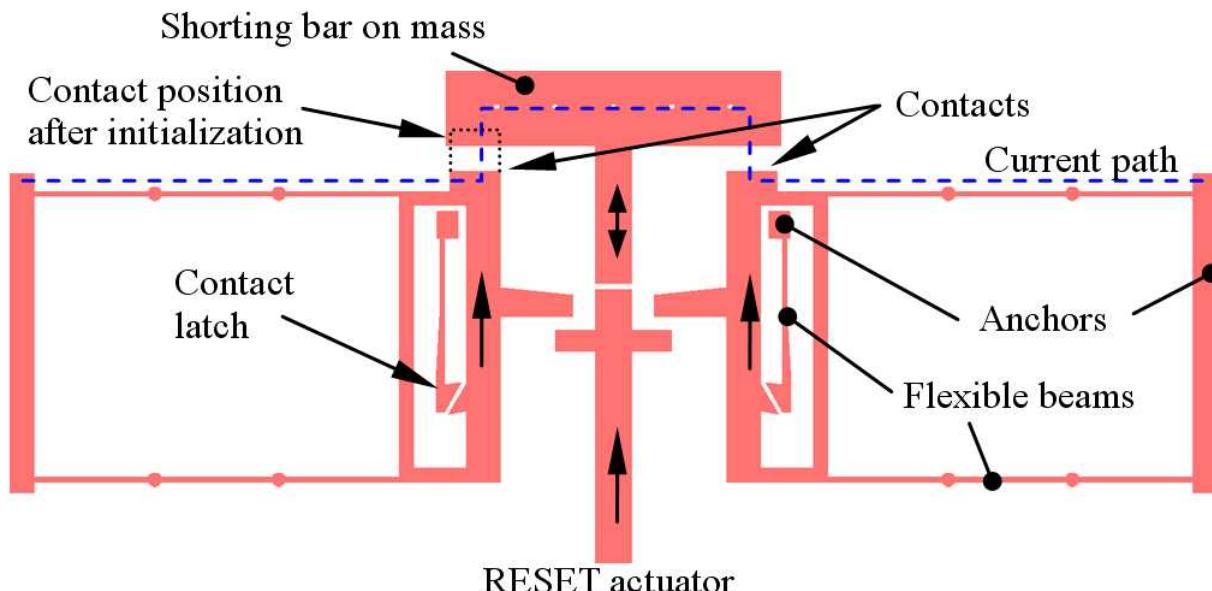
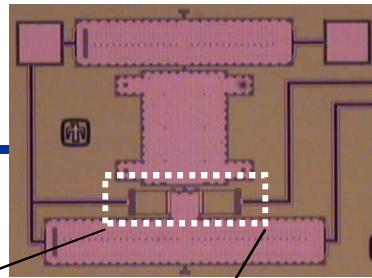
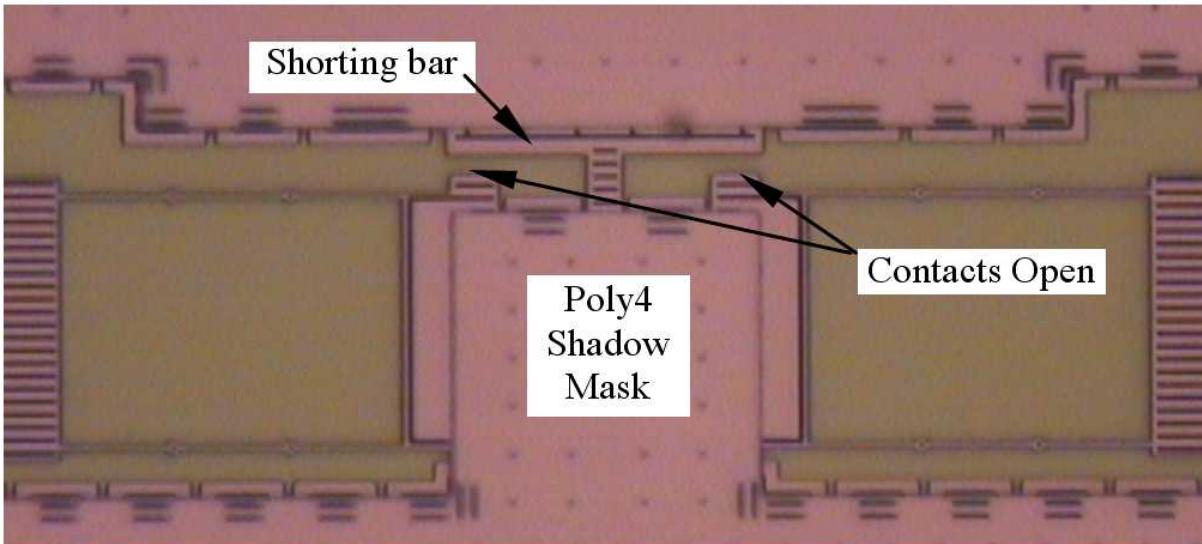


Metallization

- Metal deposited on surface using evaporation, with the die held at 45° and rotated during deposition
- Top layer of Poly used as a shadow mask for the actuators and mechanism to prevent shorting

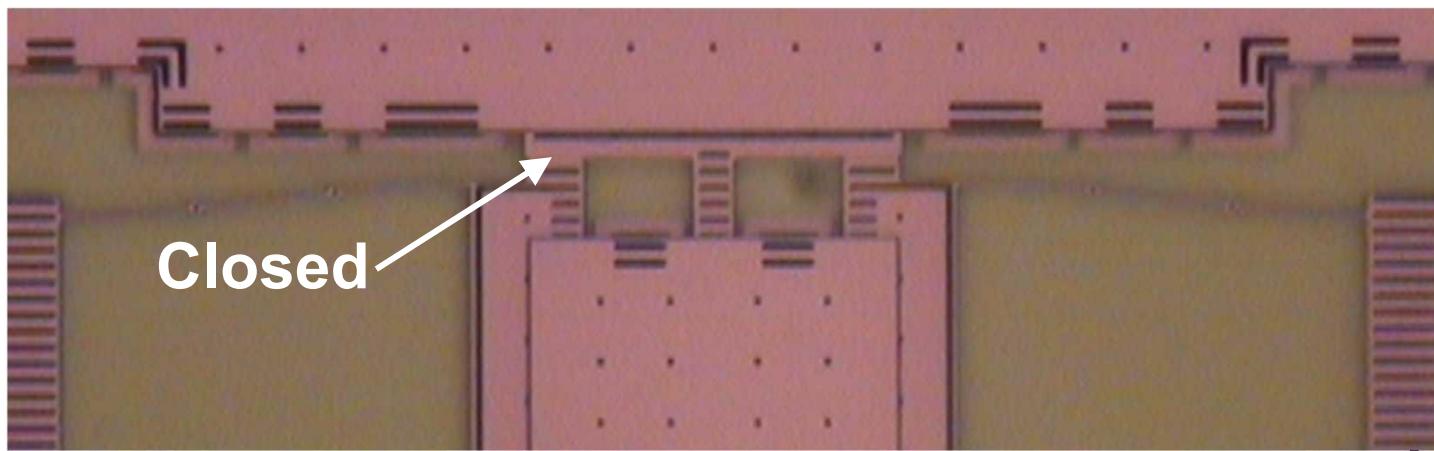
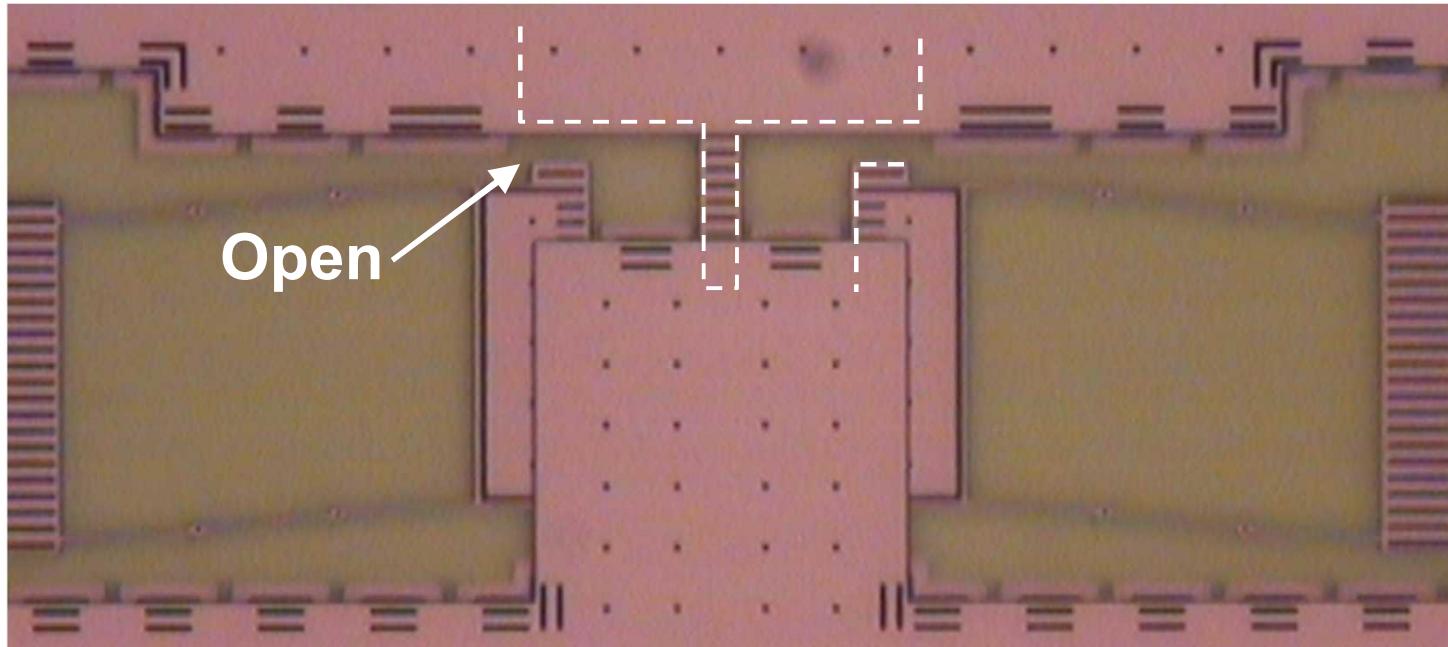


Initialization





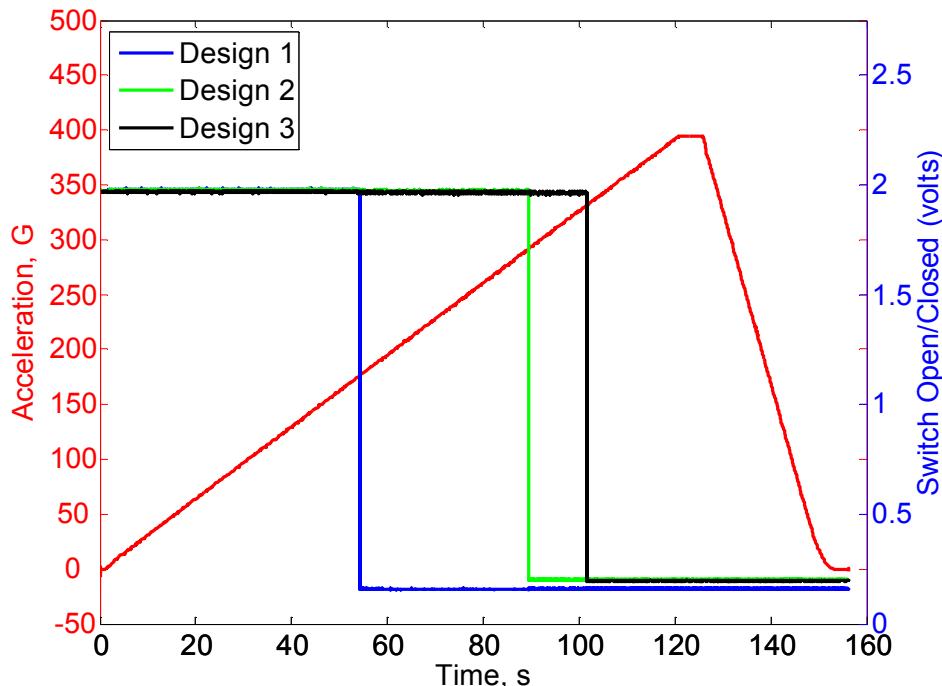
Open and Closed Positions





Centrifuge Testing

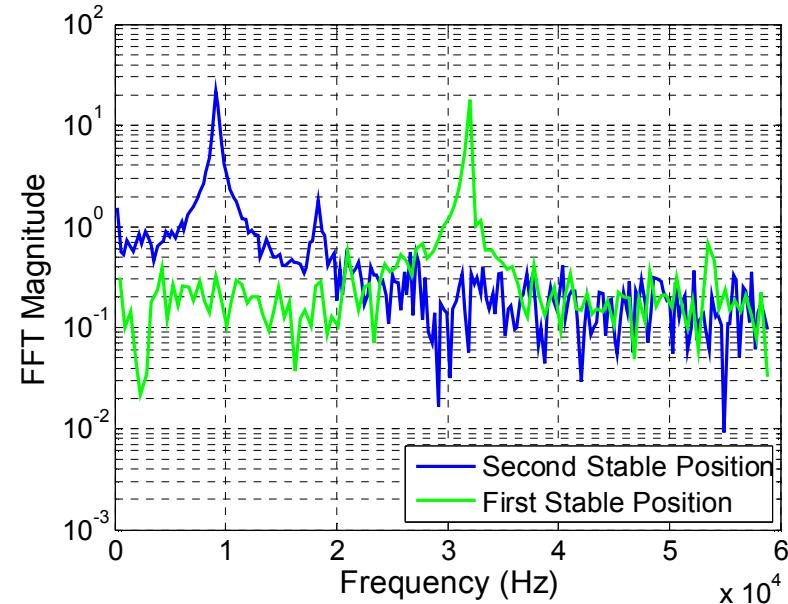
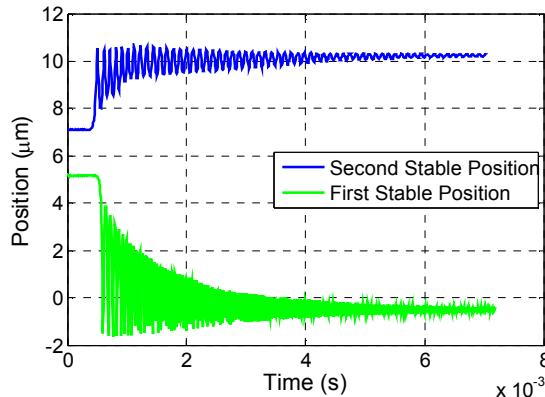
- 0g – 400g quasi-static loading
- Useful for model validation



	Measured		Modeled	
	Mean	StDev	Nominal	StDev
Design 1	153 g	25 g	84 g	4.9 g
Design 2	273 g	33 g	145 g	10 g
Design 3	*342 g	*53 g	315 g	15 g

Resonant Frequency Testing

- High-speed camera + image tracking
- Ring-down (Q in air ~ 150)
- Model validation



Measured Data

	First Stable Pos.		Second Stable Pos.	
	Position μm ± 0.125	Freq. kHz ± 0.24	Position μm ± 0.125	Freq. kHz ± 0.18
Design 1	-0.25	30.0	9.75	7.9
	-0.5	32.0	10.25	9.1
	-0.75	34.3	10.75	10.5
Design 3	0	60.9	10.5	13.9
	-0.25	63.7	10.75	15.9
	-0.25	65.7	11.25	17.7

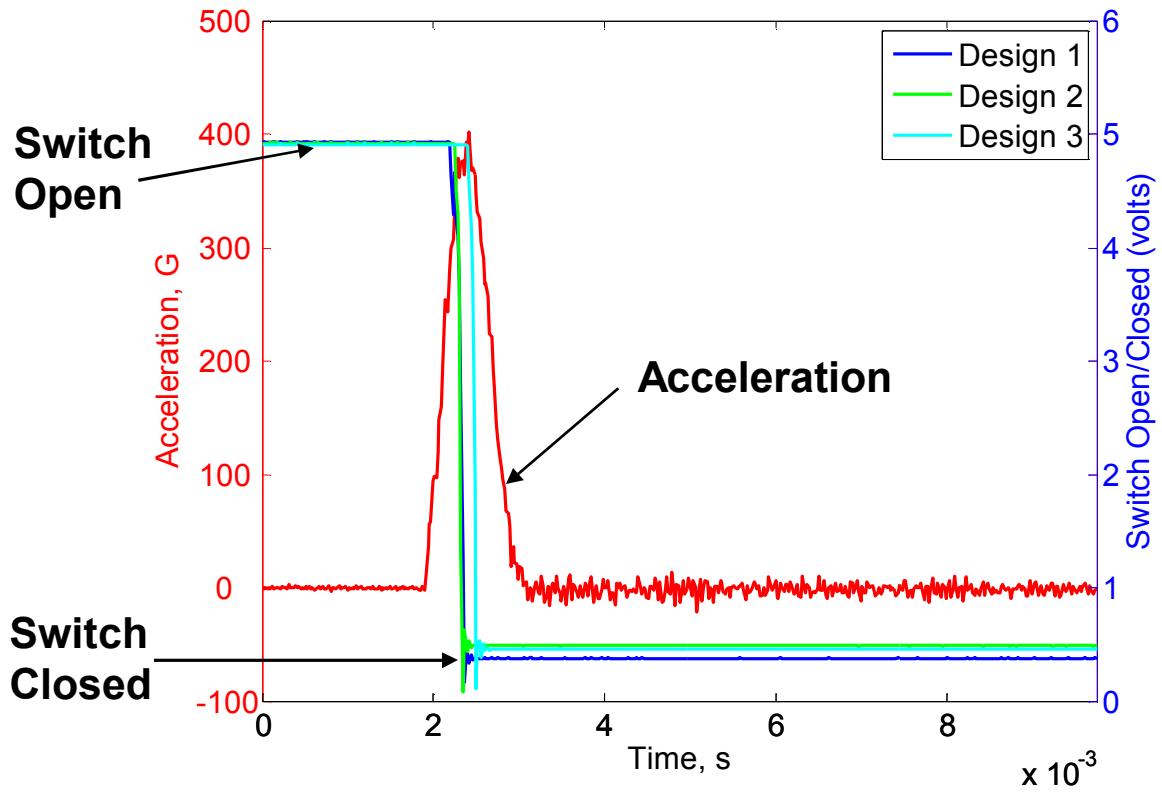
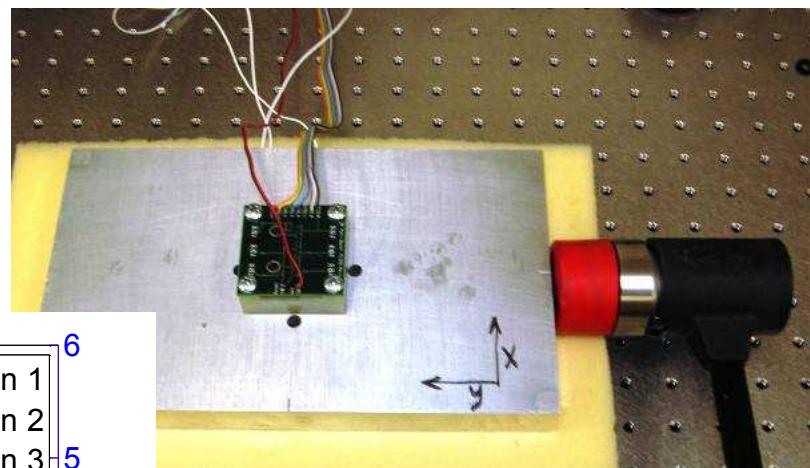
Modeled Predictions

	Mass (μg)	FSP		SSP	
		k (N/m)	f (kHz)	k (N/m)	f (kHz)
Design 1	4.013	99.8	25.1	4.32	5.2
Design 2	1.940	99.8	36.1	4.32	7.5
Design 3	1.940	223.0	54.0	9.26	11.0



Hammer Strike Testing

- 100g – 1000g discrete events
- Wide range of pulse widths and amplitudes
- Simple setup
- Multiple tests to bracket threshold





Summary

- **Presented a novel MEMS passive latching shock switch**
 - Low power, small size, latching, electrical contact, self-test, reusable
- **Demonstrated successful sensing of shock events using Hammer strike tests**
- **Used centrifuge testing and resonant frequency measurements for comparison to model predictions**
 - Original single-leg beam element model under predicting the actual response



Future Work

- **Characterize the Dynamic Behavior**
 - Acceleration vs. Pulse width
 - Frequency response (acceleration vs. frequency)
- **Evaluate the Off-Axis Sensitivity**
- **Drop Table Testing (1,000g – 15,000g)**
- **Hopkinson Bar Testing (15,000g – 50,000g)**
- **Packaging**
 - Transmissibility
 - Residual stress sensitivity (CTE mismatches)
- **Survivability**
- **Long-term Reliability**
- **Environmental Testing**
 - Temperature cycling
 - Vibration environments
 - Normal and Abnormal environments
- **More Model Development and Validation**



Questions
